



Material Content Data Sheet



Sales Product Name		BSL303SPE H6327		Issued		20. July 2018		
MA#		MA001241628						
Package		PG-TSOP6-6-6		Weight*		13.66 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.010	0.07		722	
	noble metal	gold	7440-57-5	0.038	0.28		2801	
	inorganic material	silicon	7440-21-3	0.583	4.27	4.62	42727	46250
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		86	
	non noble metal	titanium	7440-32-6	0.006	0.04		433	
	non noble metal	chromium	7440-47-3	0.018	0.13		1298	
	non noble metal	copper	7440-50-8	5.882	43.08	43.26	430733	432550
wire	non noble metal	copper	7440-50-8	0.079	0.58	0.58	5791	5791
encapsulation	organic material	carbon black	1333-86-4	0.066	0.48		4806	
	plastics	epoxy resin	-	1.411	10.33		103331	
	inorganic material	silicondioxide	60676-86-0	5.087	37.25	48.06	372474	480611
leadfinish	non noble metal	tin	7440-31-5	0.299	2.19	2.19	21888	21888
plating	noble metal	silver	7440-22-4	0.176	1.29	1.29	12910	12910
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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